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Single 2-Input NAND Gate

NL17SZ00

The NL17SZ00 is a single 2-input NAND Gate in tiny footprint packages.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.4 ns t_{PD} at $V_{CC} = 5 V (typ)$
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- IOFF Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in SC-88A, SC-74A, SOT-553, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol



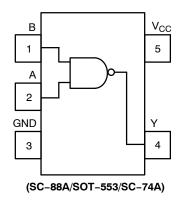
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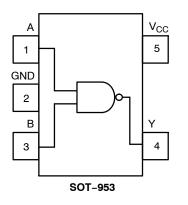
www.onsemi.com

| | | MARKING DIAGRAMS |
|-----------|---|------------------------|
| | SC-88A DF SUFFIX CASE 419A | □ □ ×× м• • • |
| E | SC-74A DBV SUFFIX CASE 318BQ | □ □ □ ××× M• ○ • |
| 10 ° ° | SOT-553 XV5 SUFFIX CASE 463B | XX M• |
| | SOT-953 P5 SUFFIX CASE 527AE | |
| | UDFN6 1.45 x 1.0 CASE 517AQ | ● ×M |
| Ŷ | UDFN6 1.0 x 1.0 CASE 517BX | 1 ° |
| XX M | = Specific Devi = Date Code* = Pb-Free Pac | |
| *Date Cod | icrodot may be in eit le orientation and/c ending upon manufa | or position may |

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.





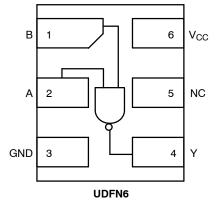


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

(SC-88A/SOT-553/SC-74A)

| Pin | Function |
|-----|-----------------|
| 1 | В |
| 2 | A |
| 3 | GND |
| 4 | Y |
| 5 | V _{CC} |

PIN ASSIGNMENT (SOT-953)

| Pin | Function |
|-----|-----------------|
| 1 | А |
| 2 | GND |
| 3 | В |
| 4 | Y |
| 5 | V _{CC} |

PIN ASSIGNMENT (UDFN)

| Pin | Function |
|-----|-----------------|
| 1 | В |
| 2 | A |
| 3 | GND |
| 4 | Y |
| 5 | NC |
| 6 | V _{CC} |

FUNCTION TABLE

| Inp | Output | |
|-----|--------|---|
| Α | В | Y |
| L | L | Н |
| L | Н | Н |
| Н | L | Н |
| Н | Н | L |

MAXIMUM RATINGS

| Symbol | Characteristics | | Value | Unit |
|-------------------------------------|--|---|---|------|
| V_{CC} | DC Supply Voltage SC-74A, SC-88A, SO | SC-88A (NLV) T-953, SOT-553, UDFN6 | -0.5 to +7.0 -0.5 to +6.5 | V |
| V _{IN} | DC Input Voltage SC-74A, SC-88A, SO | SC-88A (NLV) T-953, SOT-553, UDFN6 | -0.5 to +7.0 -0.5 to +6.5 | V |
| V _{OUT} | SC-88A (NLV) | -Mode (High or Low State) Tri-State Mode (Note 1) r-Down Mode (V _{CC} = 0 V) | -0.5 to V _{CC} + 0.5 -0.5 to +7.0 -0.5 to +7.0 | V |
| | DC Output Voltage Active- SC-74A, SC-88A, SOT-953, SOT-553, UDFN6 Powe | -0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5 | V | |
| I _{IK} | DC Input Diode Current | V _{IN} < GND | -50 | mA |
| I _{OK} | DC Output Diode Current | -50 | mA | |
| I _{OUT} | DC Output Source/Sink Current | ±50 | mA | |
| I _{CC} or I _{GND} | DC Supply Current per Supply Pin or Ground Pin | ±100 | mA | |
| T _{STG} | Storage Temperature Range | | -65 to +150 | °C |
| ΤL | Lead Temperature, 1 mm from Case for 10 secs | | 260 | °C |
| TJ | Junction Temperature Under Bias | | +150 | °C |
| θ_{JA} | Thermal Resistance (Note 2) | SC-88A SC-74A SOT-553 SOT-953 UDFN6 | 377 320 324 254 154 | °C/W |
| P _D | Power Dissipation in Still Air | ver Dissipation in Still Air SC-88A SC-74A SOT-553 SOT-953 UDFN6 | | mW |
| MSL | Moisture Sensitivity | | Level 1 | - |
| F _R | Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in | - |
| V_{ESD} | ESD Withstand Voltage (Note 3) | Human Body Model Charged Device Model | 2000 1000 | V |
| I _{Latchup} | Latchup Performance (Note 4) | | ±100 | mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
Applicable to devices with outputs that may be tri-stated.
Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Characteristics | | Min | Max | Unit |
|---------------------------------|---|---|------------------|-------------------------------|------|
| V _{CC} | Positive DC Supply Voltage | | 1.65 | 5.5 | V |
| V _{IN} | DC Input Voltage | | 0 | 5.5 | V |
| V _{OUT} | | e-Mode (High or Low State) Tri-State Mode (Note 1) er-Down Mode (V _{CC} = 0 V) | 0 0 0 | V _{CC} 5.5 5.5 | |
| T _A | Operating Temperature Range | | -55 | +125 | °C |
| t _r , t _f | Input Rise and Fall Time SC-88A (NLV) | | 0 0 | 100 20 | ns/V |
| | Input Rise and Fall Time (SC-74A, SC-88A, SOT-953, SOT-553, UDFN6) | $\begin{array}{c} V_{CC} = 1.65 \ V \ to \ 1.95 \ V \\ V_{CC} = 2.3 \ V \ to \ 2.7 \ V \\ V_{CC} = 3.0 \ V \ to \ 3.6 \ V \\ V_{CC} = 4.5 \ V \ to \ 5.5 \ V \end{array}$ | 0 0 0 0 | 20 20 10 5 | |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

| | | | Vcc | Т | م = 25°0 | 2 | –55°C ≤ T | A ≤ 125°C | |
|------------------|------------------------------|--|--|--|---|--|--|--|-------|
| Symbol | Parameter | Condition | (V) | Min | Тур | Max | Min | Max | Units |
| V _{IH} | High-Level Input | | 1.65 to 1.95 | 0.65 V _{CC} | - | _ | 0.65 V _{CC} | _ | V |
| | Voltage | | 2.3 to 5.5 | 0.70 V _{CC} | - | - | 0.70 V _{CC} | - | |
| VIL | Low-Level Input | | 1.65 to 1.95 | - | - | $0.35 V_{CC}$ | - | $0.35 V_{CC}$ | V |
| | Voltage | | 2.3 to 5.5 | - | - | 0.30 V _{CC} | - | 0.30 V _{CC} | |
| V _{OH} | High-Level Output Voltage | $ \begin{array}{l} V_{IN} = V_{IH} \mbox{ or } V_{IL} \\ I_{OH} = -100 \ \mu A \\ I_{OH} = -4 \ m A \\ I_{OH} = -8 \ m A \\ I_{OH} = -12 \ m A \\ I_{OH} = -16 \ m A \\ I_{OH} = -24 \ m A \\ I_{OH} = -32 \ m A \end{array} $ | 1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5 | V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8 | V _{CC} 1.4 2.1 2.4 2.7 2.5 4.0 | | V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8 | | V |
| V _{OL} | Low-Level Output Voltage | | 1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5 | | - 0.08 0.2 0.22 0.28 0.38 0.42 | 0.1 0.24 0.3 0.4 0.4 0.55 0.55 | | 0.1 0.24 0.3 0.4 0.4 0.55 0.55 | V |
| I _{IN} | Input Leakage Current | $V_{IN} = 5.5 \text{ V or GND}$ | 1.65 to 5.5 | - | - | ±0.1 | - | ±1.0 | μA |
| I _{OFF} | Power Off Leakage Current | V _{IN} = 5.5 V or V _{OUT} = 5.5 V | 0 | - | - | 1.0 | - | 10 | μΑ |
| I _{CC} | Quiescent Supply Current | $V_{IN} = V_{CC}$ or GND | 5.5 | - | _ | 1.0 | - | 10 | μΑ |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

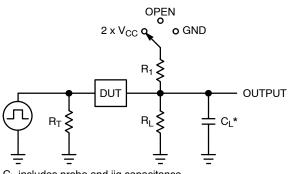
AC ELECTRICAL CHARACTERISTICS

| | | | V _{CC} | T _A = 25°C | | С | –55°C ≤ T | | |
|-------------------|------------------------------------|--------------------------------------|-----------------|-----------------------|-----|------|-----------|-----|-------|
| Symbol | Parameter | Condition | (V) | Min | Тур | Max | Min | Max | Units |
| t _{PLH,} | Propagation Delay, | R_L = 1 MΩ, C_L = 15 pF | 1.65 to 1.95 | - | 5.4 | 11.4 | - | 12 | ns |
| t _{PHL} | (A or B) to Y (Figures 3 and 4) | R_L = 1 M Ω , C_L = 15 pF | 2.3 to 2.7 | - | 3.0 | 6.5 | - | 7.0 | |
| | | R_L = 1 M Ω , C_L = 15 pF | 3.0 to 3.6 | - | 2.4 | 4.5 | - | 4.7 | |
| | | R_L = 500 Ω , C_L = 50 pF | | - | 2.4 | 5.0 | - | 5.2 | |
| | | R_L = 1 M Ω , C_L = 15 pF | 4.5 to 5.5 | - | 2.0 | 3.9 | - | 4.1 | |
| | | R_L = 500 Ω , C_L = 50 pF | | - | 2.4 | 4.3 | - | 4.5 | |

CAPACITIVE CHARACTERISTICS

| Symbol | Parameter | Condition | Typical | Units |
|------------------|---|---|---------|-------|
| C _{IN} | Input Capacitance | V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} | 2.5 | pF |
| C _{OUT} | Output Capacitance | V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} | 2.5 | pF |
| C _{PD} | Power Dissipation Capacitance (Note 5) | 10 MHz, V_{CC} = 3.3 V, V_{IN} = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} | 9 11 | pF |

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

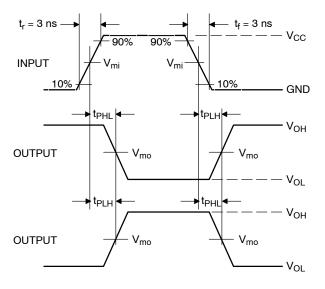


| Switch Position | C _L , pF | R_{L}, Ω | R ₁ , Ω | | |
|--------------------|---|--|--|--|--|
| Open | See AC Characteristics Table | | | | |
| $2 \times V_{CC}$ | 50 | 500 | 500 | | |
| GND | 50 | 500 | 500 | | |
| | Position Open 2 x V _{CC} | Position See AC Character Open See AC Character 2 x V _{CC} 50 | Position See AC Characteristics Tall 0pen See AC Characteristics Tall 2 x V _{CC} 50 | | |

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit



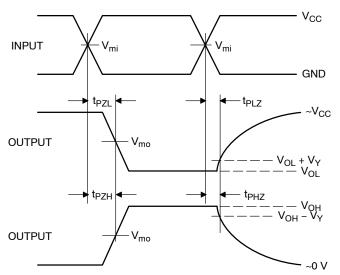


Figure 4. Switching Waveforms

| | | Vm | | |
|---------------------|---------------------|-------------------------------------|---|--------------------|
| V _{CC} , V | V _{mi} , V | t _{PLH} , t _{PHL} | t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ} | V _Y , V |
| 1.65 to 1.95 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.15 |
| 2.3 to 2.7 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.15 |
| 3.0 to 3.6 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.3 |
| 4.5 to 5.5 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.3 |

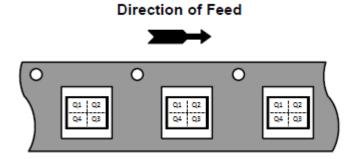
DEVICE ORDERING INFORMATION

| Device | Packages | Specific Device Code | Pin 1 Orientation (See below) | Shipping⁺ |
|------------------------------------|-------------------------|------------------------|----------------------------------|--------------------|
| NL17SZ00DFT2G | SC-88A | L1 | Q4 | 3000 / Tape & Reel |
| NLV17SZ00DFT2G* | SC-88A | L1 | Q4 | 3000 / Tape & Reel |
| NL17SZ00DBVT1G | SC-74A | AA | Q4 | 3000 / Tape & Reel |
| NL17SZ00XV5T2G | SOT-553 | L1 | Q4 | 4000 / Tape & Reel |
| NL17SZ00P5T5G | SOT-953 | 3 (Rotated 90° CW) | Q2 | 8000 / Tape & Reel |
| NL17SZ00MU1TCG (In Development) | UDFN6, 1.45 x 1.0, 0.5P | TBD | Q4 | 3000 / Tape & Reel |
| NL17SZ00MU3TCG (In Development) | UDFN6, 1.0 x 1.0, 0.35P | Y (Rotated 90° CCW) | Q4 | 3000 / Tape & Reel |

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

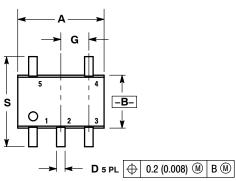
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

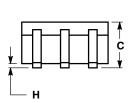
Pin 1 Orientation in Tape and Reel

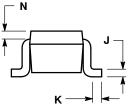


PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE L



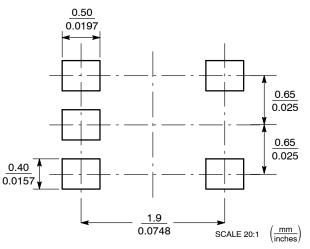




NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| | INCHES | | MILLIMETERS | | |
|-----|-----------|-------|-------------|------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 0.071 | 0.087 | 1.80 | 2.20 | |
| В | 0.045 | 0.053 | 1.15 | 1.35 | |
| С | 0.031 | 0.043 | 0.80 | 1.10 | |
| D | 0.004 | 0.012 | 0.10 | 0.30 | |
| G | 0.026 BSC | | 0.65 BSC | | |
| Н | | 0.004 | | 0.10 | |
| J | 0.004 | 0.010 | 0.10 | 0.25 | |
| K | 0.004 | 0.012 | 0.10 | 0.30 | |
| Ν | 0.008 REF | | 0.20 REF | | |
| S | 0.079 | 0.087 | 2.00 | 2.20 | |

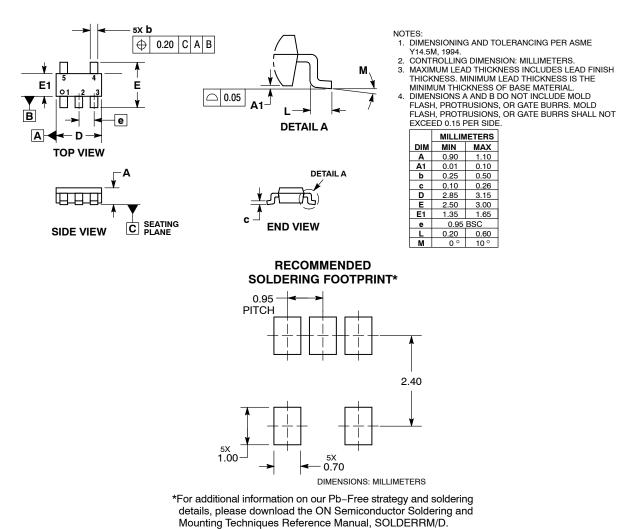
SOLDER FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

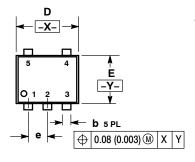
PACKAGE DIMENSIONS

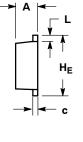
SC-74A CASE 318BQ ISSUE B



PACKAGE DIMENSIONS

SOT-553, 5 LEAD CASE 463B ISSUE C



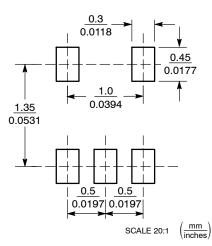


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| THICKNESS OF BASE MATERIAL. | |
|-----------------------------|------|
| | |

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.50 | 0.55 | 0.60 | 0.020 | 0.022 | 0.024 |
| b | 0.17 | 0.22 | 0.27 | 0.007 | 0.009 | 0.011 |
| С | 0.08 | 0.13 | 0.18 | 0.003 | 0.005 | 0.007 |
| D | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |
| E | 1.15 | 1.20 | 1.25 | 0.045 | 0.047 | 0.049 |
| е | 0.50 BSC | | | 0.020 BSC | | |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 |
| HE | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |

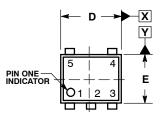
SOLDERING FOOTPRINT*



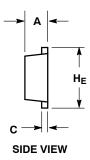
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

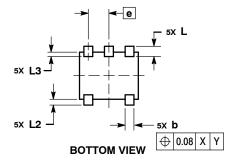
PACKAGE DIMENSIONS

SOT-953 CASE 527AE ISSUE E



TOP VIEW

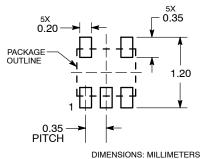




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

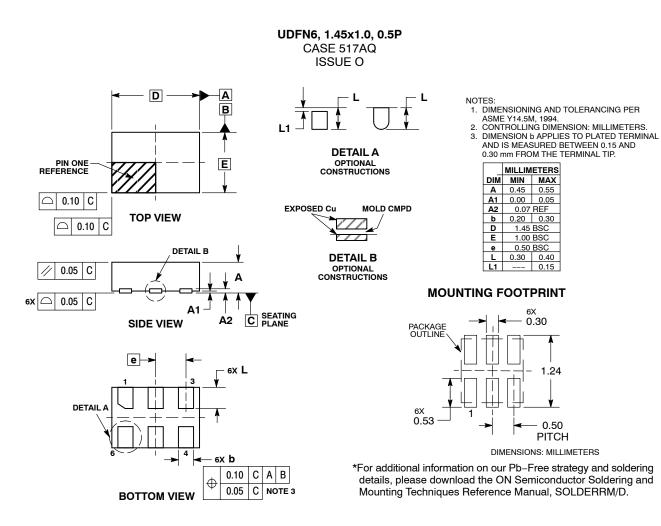
| | MILLIMETERS | | | |
|-----|-------------|------|------|--|
| DIM | MIN | NOM | MAX | |
| Α | 0.34 | 0.37 | 0.40 | |
| b | 0.10 | 0.15 | 0.20 | |
| С | 0.07 | 0.12 | 0.17 | |
| D | 0.95 | 1.00 | 1.05 | |
| Ш | 0.75 | 0.80 | 0.85 | |
| е | 0.35 BSC | | | |
| HE | 0.95 | 1.00 | 1.05 | |
| L | 0.175 REF | | | |
| L2 | 0.05 | 0.10 | 0.15 | |
| L3 | | | 0.15 | |

SOLDERING FOOTPRINT*

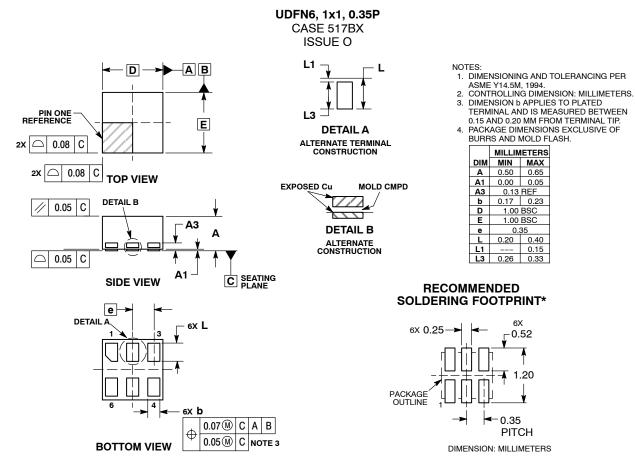


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PACKAGE DIMENSIONS



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